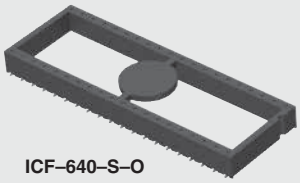
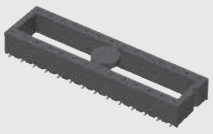
samtec


ICF–640–S–O

ICF–328–T–O



ICF–314–S–O

(2.54 mm) .100"

ICF SERIES

SURFACE MOUNT DIP SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ICF

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Sn or Au over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(2.54 mm) .100" to
(3.81 mm) .150"
Insertion Force/Contact:
(1.39 N) 5 oz average
Withdrawal Force/Contact:
(1.11 N) 4 oz average
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.15 mm) .006" max*
*(.004" stencil solution may be available; contact IPG@samtec.com)

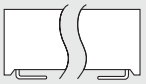
RECOGNITIONS

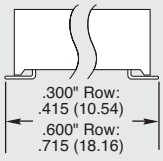
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

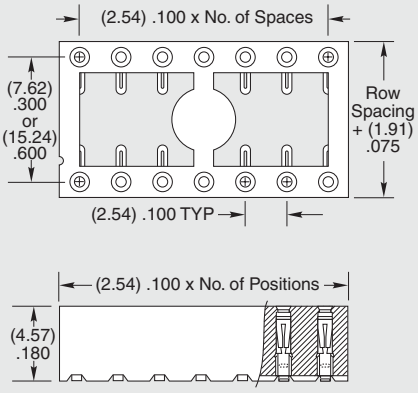
Note:
Some sizes, styles and options are non-standard, non-returnable.

TYPE SOCKET	ROW SPACING & NO. OF CONTACTS	PLATING OPTION	TAIL OPTION	OTHER OPTION
ICF =Surface Mount IC Socket		**–S** =30 µ" (0.76µm) Gold on contact, Matte Tin on tail **–T** = Matte Tin	**–I** =Tails In **–O** =Tails Out	**–TR** =Tape & Reel Packaging





Specify from chart below



"–XXX"	Row Space	No. of Contacts
–308	(7.62) .300	08
–314		14
–316		16
–318		18
–320		20
–328		28
–624	(15.24) .600	24
–628		28
–632		32
–640		40

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.